

EN: This Datasheet is presented by the manufacturer.

Please visit our website for pricing and availability at www.hestore.hu.

MMDL914T1G, SMMDL914T1G, MMDL914T3G

High-Speed Switching Diode

Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	V_{R}	100	V
Forward Current	IF	200	mA
Non-Repetitive Peak Forward Surge Current 60 Hz	I _{FSM(surge)}	500	mA
Repetitive Peak Forward Current (Note 2)	I _{FRM}	1.0	Α
Non-Repetitive Peak Forward Current (Square Wave, $T_J = 25^{\circ}C$ prior to surge) $t = 1 \ \mu s$ $t = 10 \ \mu s$ $t = 100 \ \mu s$ $t = 1 \ ms$ $t = 1 \ s$	I _{FSM}	36.0 18.0 6.0 3.0 0.7	А

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board T _A = 25°C (Note 1)	P_{D}	200	mW
Derate above 25°C		1.57	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{ hetaJA}$	635	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to 150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. FR-4 Minimum Pad.
- 2. Square Wave, f = 40 kHz, PW = 200 nsTest Duration = 60 s, $T_J = 25^{\circ}\text{C}$ prior to surge.



ON Semiconductor®

http://onsemi.com



SOD-323 CASE 477 STYLE 1



MARKING DIAGRAM



5D = Specific Device Code

M = Date Code

■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

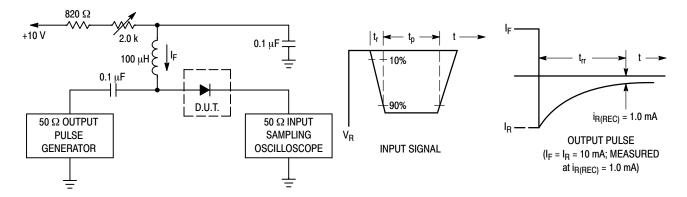
Device	Package	Shipping [†]
MMDL914T1G	SOD-323 (Pb-Free)	3,000 / Tape & Reel
SMMDL914T1G	SOD-323 (Pb-Free)	3,000 / Tape & Reel
MMDL914T3G	SOD-323 (Pb-Free)	10,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MMDL914T1G, SMMDL914T1G, MMDL914T3G

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS	·		•	
Reverse Breakdown Voltage (I _R = 100 μAdc)	V _(BR)	100	=	Vdc
Reverse Voltage Leakage Current (V _R = 20 Vdc) (V _R = 75 Vdc)	I _R	- -	25 5.0	nAdc μAdc
Diode Capacitance (V _R = 0 V, f = 1.0 MHz)	C _T	-	4.0	pF
Forward Voltage (I _F = 10 mAdc)	V _F	-	1.0	Vdc
Reverse Recovery Time (I _F = I _R = 10 mAdc) (Figure 1)	t _{rr}	-	4.0	ns

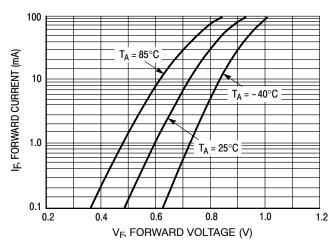


Notes: 1. A 2.0 $k\Omega$ variable resistor adjusted for a Forward Current (I_F) of 10 mA.

- 2. Input pulse is adjusted so $I_{R(peak)}$ is equal to 10 mA.
- 3. t_p » t_{rr}

Figure 1. Recovery Time Equivalent Test Circuit

MMDL914T1G, SMMDL914T1G, MMDL914T3G



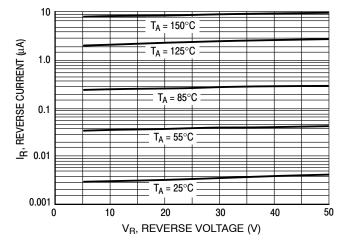


Figure 2. Forward Voltage

Figure 3. Leakage Current

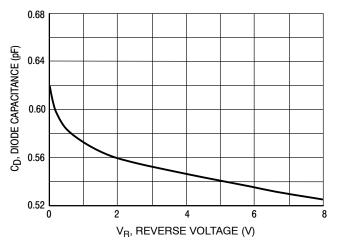


Figure 4. Capacitance

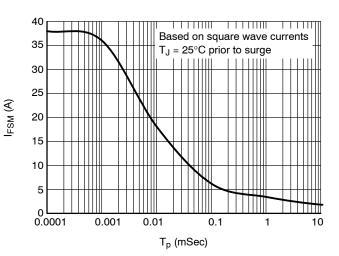
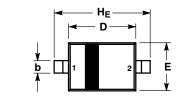


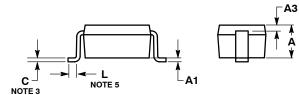
Figure 5. Maximum Non-repetitive Peak Forward Current as a Function of Pulse Duration, Typical Values

MMDL914T1G, SMMDL914T1G, MMDL914T3G

PACKAGE DIMENSIONS

SOD-323 CASE 477-02 **ISSUE H**





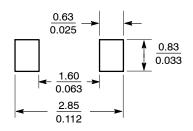
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETERS. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- DIMENSION L IS MEASURED FROM END OF RADIUS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
А3	0.15 REF		0.006 REF		F	
b	0.25	0.32	0.4	0.010	0.012	0.016
С	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
He	2.30	2.50	2.70	0.090	0.098	0.105

STYLE 1: PIN 1. CATHODE (POLARITY BAND)

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent—Marking.pdf. SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA **Phone**: 303–675–2175 or 800–344–3860 Toll Free USA/Canada **Fax**: 303–675–2176 or 800–344–3867 Toll Free USA/Canada

Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center

Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative